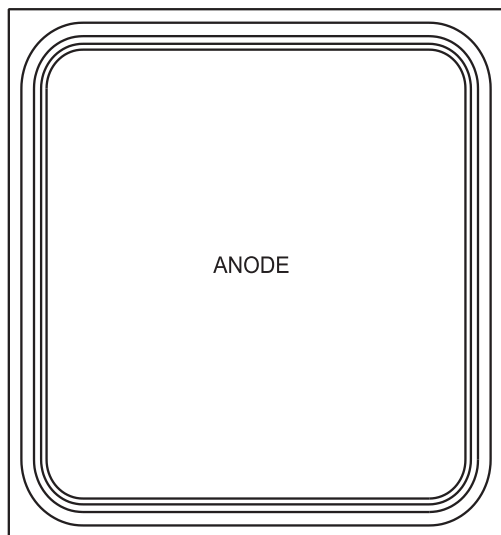


**PROCESS DETAILS**

|                        |                  |
|------------------------|------------------|
| Die Size               | 72.5 x 72.5 MILS |
| Die Thickness          | 11.8 MILS        |
| Anode Bonding Pad Area | 63.8 x 63.8 MILS |
| Top Side Metalization  | Al - 30,000Å     |
| Back Side Metalization | Au - 18,000Å     |

**GEOMETRY**



BACKSIDE CATHODE

R0

**GROSS DIE PER 4 INCH WAFER**

2,178

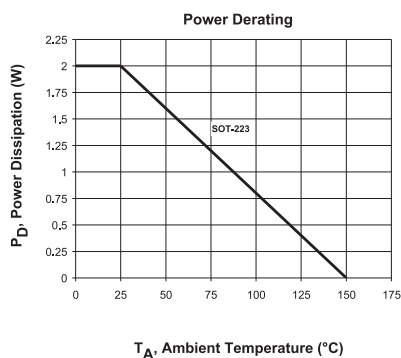
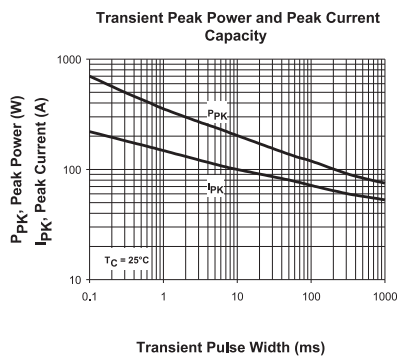
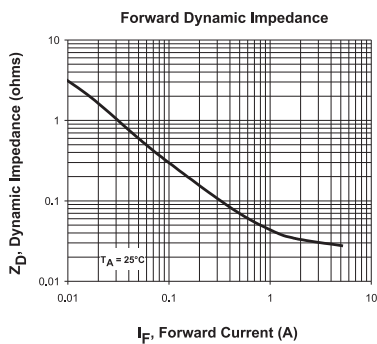
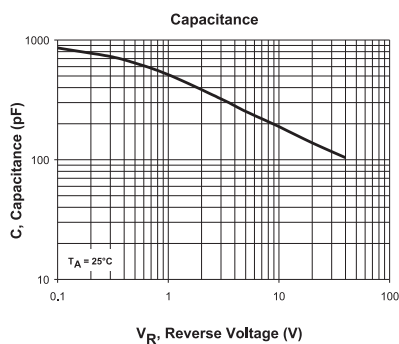
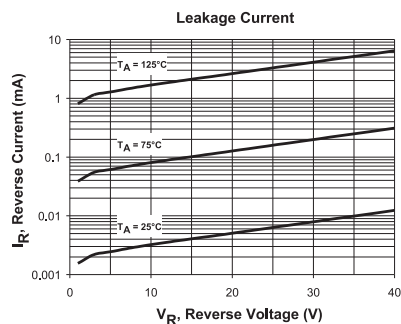
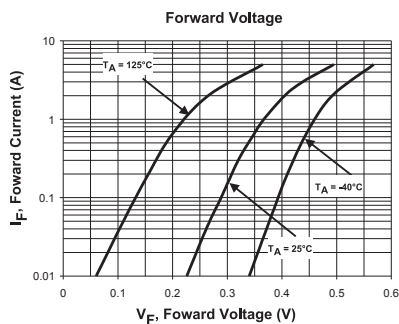
**PRINCIPAL DEVICE TYPES**

CZSH5-40

CZSH10-40CN (Dual Chip)

145 Adams Avenue  
Hauppauge, NY 11788 USA  
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